

**AMENDMENTS TO THE CLAIMS:**

***Claims 1-20 (cancelled)***

21. (Currently Amended) The method according to claim ~~20~~ 37, wherein printing material onto a required portion of a substrate and a test portion of said substrate comprises using a mask such that said material is printed onto a specific location of said required portion of said substrate and a specific location of said test portion of said substrate.

***Claims 22-29 (cancelled)***

30. (Currently Amended) The method according to claim ~~29~~ 21, wherein said test portion corresponds to an area of said substrate that is at a higher risk of resulting in a defect of said material when printed thereon than is said required portion when said material is printed thereon by corresponding to an area of said substrate that is located outside of said required portion and along a peripheral edge of said substrate.

31. (Previously Added) The method according to claim 30, wherein said material is printed onto said test portion under a condition that has a high risk of resulting in a defect of said material when printed on said test portion by printing said material under a condition that is at a higher risk of resulting in a defect of said material when printed on said test portion than is a condition under which said material is printed on said required portion.

32. (Previously Added) The method according to claim 31, wherein said material is printed under a condition that is at a higher risk of resulting in a defect of said material when printed on said test portion than is a condition under which said material is printed on said required portion by printing said material through an opening in said mask onto said specific location of said test portion that is smaller in size than any opening in said mask through which said material is printed onto said specific location of said required portion.

33. (Currently Amended) The method according to claim ~~29~~ 21, wherein said material is printed onto said test portion under a condition that has a high risk of resulting in a defect of said material when printed on said test portion by printing said material under a condition that is at a higher risk of resulting in a defect of said material when printed on said test portion than is a condition under which said material is printed on said required portion.

***Claim 34 (cancelled)***

35. (Previously Added) The method according to claim ~~34~~ 45, wherein said material is printed under a condition that is at a higher risk of resulting in a defect of said material when printed on said test portion than is a condition under which said material is printed on said required portion by printing said material through an opening in said mask onto said specific location of said test portion that is smaller in size than any opening in said mask through which said material is printed onto said specific location of said required portion.

36. (Previously Added) The method according to claim 35, wherein said test portion corresponds to an area of high risk by corresponding to an area of said substrate that is at a higher risk of resulting in a defect of said material when printed thereon than is said required portion when said material is printed thereon.

37. (Currently Amended) A method for determining a printing state of material on a substrate, comprising:

printing material onto a required portion of a substrate and a test portion of said substrate, wherein said test portion corresponds to an area of said substrate ~~The method according to claim 20, wherein said test portion corresponds to an area of high risk by corresponding to an area of said substrate~~ that is at a higher risk of resulting in a defect of said material when printed thereon than is said required portion when said material is printed thereon, and wherein said material is printed onto

said test portion under a condition that has a high risk of resulting in a defect of said material when printed on said test portion; and

judging a printing state of said material printed onto said required portion by inspecting a printing state of said material printed onto said test portion.

38. (Previously Added) The method according to claim 37, wherein said test portion corresponds to an area of said substrate that is at a higher risk of resulting in a defect of said material when printed thereon than is said required portion when said material is printed thereon by corresponding to an area of said substrate that is located outside of said required portion and along a peripheral edge of said substrate.

39. (Previously Added) The method according to claim 38, wherein said material is printed onto said test portion under a condition that has a high risk of resulting in a defect of said material when printed on said test portion by printing said material under a condition that is at a higher risk of resulting in a defect of said material when printed on said test portion than is a condition under which said material is printed on said required portion.

40. (Previously Added) The method according to claim 39, wherein said material is printed under a condition that is at a higher risk of resulting in a defect of said material when printed on said test portion than is a condition under which said material is printed on said required portion by printing said material onto a location of said test portion that is smaller in size than any location of said required portion onto which said material is printed.

41. (Previously Added) The method according to claim 37, wherein said material is printed onto said test portion under a condition that has a high risk of resulting in a defect of said material when printed on said test portion by printing said material under a condition that is at a higher risk of resulting in a defect of said material when printed on said test portion than is a condition under which said material is printed on said required portion.

42. (Currently Amended) A method for determining a printing state of material on a substrate, comprising:

printing material onto a required portion of a substrate and a test portion of said substrate, wherein said test portion corresponds to an area of said substrate that is at high risk of resulting in a defect of said material when printed thereon ~~The method according to claim 20, and~~ wherein said material is printed onto said test portion under a condition that ~~has a high risk of resulting in a defect of said material when printed on said test portion by printing said material under a condition that is~~ at a higher risk of resulting in a defect of said material when printed on said test portion than is a condition under which said material is printed on said required portion.

43. (Previously Added) The method according to claim 42, wherein said material is printed under a condition that is at a higher risk of resulting in a defect of said material when printed on said test portion than is a condition under which said material is printed on said required portion by printing said material onto a location of said test portion that is smaller in size than any location of said required portion onto which said material is printed.

44. (Previously Added) The method according to claim 43, wherein said test portion corresponds to an area of high risk by corresponding to an area of said circuit board that is at a higher risk of resulting in a defect of said material when printed thereon than is said required portion when said material is printed thereon.

45. (New) The method according to claim 42, wherein printing material onto a required portion of a substrate and a test portion of said substrate comprises using a mask such that said material is printed onto a specific location of said required portion of said substrate and a specific location of said test portion of said substrate.